

Variant: 001  
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**PMP21055 REV A Bill of Materials**

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1	1	6.8pF	GRM1555C1H6R8CA01D	MuRata	CAP, CERM, 6.8 pF, 50 V, +/- 5%, COG/NP0, 0402	0402
2	C2, C3, C4, C5, C6, C8, C9	7	10uF	GRM155R61A106ME11	MuRata	CAP, CERM, 10 µF, 10 V, +/- 20%, X5R, 0402	0402
3	C7	1	0.1uF	GRM155R61A104KA01D	MuRata	CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	0402
4	L1, L2	2	2.2uH	XPL2010-222MLB	Coilcraft	Inductor, Shielded, Composite, 2.2 µH, 1.3 A, 0.16 ohm, SMD	XPL2010
5	R1	1	41.2k	CRCW040241K2FKED	Vishay-Dale	RES, 41.2 k, 1%, 0.063 W, 0402	0402
6	R2	1	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
7	TP1, TP2	2		5010	Keystone	Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint
8	TP3, TP4	2		5011	Keystone	Test Point, Multipurpose, Black, TH	Black Multipurpose Testpoint
9	U1	1		TPS61021ADSGR	Texas Instruments	3-A Boost Converter with 0.5-V Ultra Low Input Voltage, DSG0008A (WSON-8)	DSG0008A
10	U2	1		TPS62743YFPR	Texas Instruments	Ultra-low-power DCDC converter in WCSP, YFP0008AGAC (DSBGA-8)	YFP0008AGAC

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